

**J.C. PATENTS**  
4 VENTURE, SUITE 250  
IRVINE, CALIFORNIA 92618  
TEL.: (949) 660-0761  
FAX: (949) 660-0809  
E-MAIL: [jcpi@email.msn.com](mailto:jcpi@email.msn.com)

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**CERTIFICATE OF TRANSMISSION****September 20, 2002**

<b>Atty Docket No.:</b>	JCLA8676
<b>Appl. No.:</b>	10/055,580
<b>Filing Date:</b>	January, 22, 2002
<b>Pages:</b>	Cover + 9

**BY FACSIMILE ONLY**

**Fax No.:** 703-872-9318  
**Attention:** Examiner MITCHELL, JAMES M.  
**Group Unit:** 2827  
**From:** Jiawei Huang, Reg. No. 43,330  
**MESSAGE:** Enclosed is an Amendment in 9 pages.

**FAX COPY RECEIVED****SEP 20 2002**

TECHNOLOGY CENTER 2800

Sir:

I hereby certify that this correspondence is being facsimile transmitted to the Patent and Trademark Office on **September 20, 2002** at the above indicated fax number.

Sign by: *M. Chang*  
Michelle Chang

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## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Application No.: 10/055,580  
Filed: January 22, 2001  
For: Cylindrical Bonding Structure and Method  
of Manufacture

Applicant: Lee et al.  
Examiner: Mitchell, James M  
Art Unit 2827

#6/B  
9/25/02  
Jum.

## AMENDMENT

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Assistant Commissioner of Patents and Trademarks  
Washington, DC 20231

SEP 20 2002

TECHNOLOGY CENTER 2800

Sir:

In response to the Office Action dated July 5, 2002, please enter the following amendments and consider the following remarks.

IN THE CLAIMS

Please cancel 1-11 without prejudice or disclaimer.

Please substitute the following clean copy text claims for the pending claims of the number.

36. (Amended) A cylindrical bonding structure on a silicon chip such that the structure may flip over and connect with a substrate, wherein the chip has at least one bonding pad and the substrate has a substrate surface having a patterned solder mask and at least one junction pad thereon, and the patterned solder mask layer has at least an opening that exposes the junction pad, the cylindrical bonding structure comprising:

a conductive cylinder on the bonding pad of the chip; and

a cylindrical solder cap on the conductive cylinder, wherein the cylindrical solder cap has an outer diameter smaller than the diameter of the opening in the patterned solder mask and a length greater than the depth of the opening, and the solder material has a melting point lower than the conductive cylinder material.